2019 CMPUG SPRING MEETING – FINAL AGENDA

TOPIC: *Advances in CMP Consumables, Materials and Tools*

Meeting Date: April 11, 2019
Time: 1:00 pm - 6:00 pm
Location: Micron Technology Boise
Bldg 17, 8000 S. Federal Way
Boise, ID 83707
Parking: PARKING: Available in Building 17C parking lot.

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FREE CONFERENCE REGISTRATION

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Chair (Co-Chair):
Michael Pevny, 3M, mpevny@mmm.com
Andrew Carswell, Micron Technology, acarswell@micron.com

SPEAKERS/AGENDA

12:30 pm – Registration/Badge Pick up at Bldg 17 lobby entrance

1:00 pm – Welcome and Acknowledgment of sponsors by Co-Chairs Michael Pevny (3M) and Andrew Carswell (Micron Technology)

1:10 pm – Keynote Talk, Suresh Ramarajan, Senior Director NVM Process Development Engineering, Micron Technology

1:40 pm – "Method for Studying the Effect of Conditioner Design and Polisher Kinematics on Fluid Flow Characteristics during CMP", Juan Cristobal Mariscal, University of Arizona

2:05 pm – "Low Particle Size Ceria STI Slurry Designed for High Performance Dishing and Nitride Loss", Edmund Chu, Ferro

2:30 pm – "The Development of Post-CMP Cleans to Address New Challenges in Advanced Device Manufacturing", Paul Bernatis, DuPont EKC Technology

2:55 pm – Coffee Break/Poster Session/Networking

3:40 pm – "Effect of Conditioner Wear on the Tribological, Thermal, Kinetic and Pad Microtextural Characteristics in ILD CMP", Hossein Dadashazar, University of Arizona

4:05 pm – "Computer Simulation for Understanding of CMP Process", Akira Endou, Fujimi Incorporated

4:30 pm – "High Quality Test Wafer and Analysis For CMP Process, Consumables and Materials", Yasuji Moriki, AMT

4:55 pm – "Okamoto 300mm Final Polish System", Bob Pinto, Okomoto

5:20 pm – ICPT and CAMP Announcement, Sponsor Announcement

5:30 pm – Concluding remarks by Co-Chairs Michael Pevny and Andrew Carswell

5:40 pm – Meeting Adjourn

6:30 pm – Gratis Dinner Located at El Tanampa Mexican Restaurant, 7802 W. Spectrum St., Boise